Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	195	(interlayer or interlevel or ild) same (slot or hole or via or opening or slit) same (gate near stack)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:45
L2	139	(interlayer or interlevel or ild) same (slot or hole or via or opening or slit) same (gate near stack) same (active or source or drain or source/drain)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:46
13	8	(interlayer or interlevel or ild) same (slot or hole or via or opening or slit) same (gate near stack) same (active or source or drain or source/drain) and contactless	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:48
L4	2	(interlayer or interlevel or ild) same (slot or slit) same (gate near stack) same (active or source or drain or source/drain) and contactless	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:48
L5	9	(interlayer or interlevel or ild) same (slot or slit) same (gate near stack) same (active or source or drain or source/drain)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:50
L6	3284	contactless and (slot or slit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:50
L7	337	contactless and ((dimension or dimensional or width or length) near5 (slot or slit))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:50
L8	64	contactless and ((dimension or dimensional or width or length) near5 (slot or slit)) and gate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:50
L9	50	contactless and ((dimension or dimensional or width or length) near5 (slot or slit)) and gate and memory	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:52

L10	11	contactless and ((dimension or dimensional or width or length) near5 (slot or slit)) and gate and memory and word and bit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:53
L11	66	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) and gate and memory and word and bit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:54
L12 ·	3	contactless same ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) and gate and memory and word and bit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:54
L13	0	contactless same ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate and memory and word and bit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:54
L14	40	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate and memory and word and bit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:54
L15	15	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate same memory and word and bit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:54
L16	8	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate same memory same word and bit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:54
L17	8	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate same memory same word same bit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:55
L18	0	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate same memory same word same bit and ((slot or slit or opening or hole or via) near10 (lithography or photolithography))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM <u>*</u> TDB	OR	ON	2007/12/05 11:55

L19	0	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate same memory same word same bit and ((slot or slit or opening or hole or via) with (lithography or photolithography))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:56
L20	1	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate same memory same word same bit and ((slot or slit or opening or hole or via) same (lithography or photolithography))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:56
L21	1	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate same memory same word same bit and ((slot or slit or opening or hole or via) same (image or imaging or imaged or lithography or photolithography))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:56
L22	1	contactless and ((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate same memory same word same bit and ((slot or slit or opening or hole or via) near10 (image or imaging or imaged or lithography or photolithography))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:57
L23	14	((dimension or dimensional or width or length) near5 (hole or opening or via or slot or slit)) same gate same memory same word same bit and ((slot or slit or opening or hole or via) near10 (image or imaging or imaged or lithography or photolithography))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 11:59
L24	19	"5734607"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:00

L25	14	("20020038911" "5091326" "5734 607" "5734607" "6107670" "6197 639" "6495467" "6765258").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:03
L26	1	I25 and contactless	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:02
L27	7	l25 and (slot or slit or via or opening or hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:02
L28	3	I25 and ((bit or bitline) near10 (slot or slit or via or opening or hole))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:03
L29	3	I25 and ((bit or bitline) with (slot or slit or via or opening or hole)) with (contact or contactless)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:03
L30	15	("20020038911" "5091326" "5734 607" "5734607" "6107670" "6197 639" "6495467" "6765258").PN. or 10/751193	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:03
L31	4	I30 and ((bit or bitline) with (slot or slit or via or opening or hole)) with (contact or contactless)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:04
L32	2	I30 and ((bit or bitline) with (slot or slit or via or opening or hole)) with (contact or contactless) with (insulating or dielectric or ild or interlayer or inter-layer or interlevel or inter-level)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:06
L33	3	I30 and ((bit or bitline) with (slot or slit or via or opening or hole)) same (contact or contactless) same (insulating or dielectric or ild or interlayer or inter-layer or interlevel or inter-level)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:06

L34	3	I30 and ((bit or bitline) same (slot or slit or via or opening or hole)) same (contact or contactless) same (insulating or dielectric or ild or interlayer or inter-layer or interlevel or inter-level)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:06
L35	1	I30 and ((bit or bitline) same (slot or slit or via or opening or hole)) same (contact or contactless) same (insulating or dielectric or ild or interlayer or inter-layer or interlevel or inter-level) and ((slot or slit or via or opening or hole) near10 (dimension or width or length or longer or shorter or larger))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:07
L36	2106	((bit or bitline) same (slot or slit or via or opening or hole)) same (contact or contactless) same (insulating or dielectric or ild or interlayer or inter-layer or interlevel or inter-level) and ((slot or slit or via or opening or hole) near10 (dimension or width or length or longer or shorter or larger))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:07
L37	618	((bit or bitline) same (slot or slit or via or opening or hole)) same (contact or contactless) same (insulating or dielectric or ild or interlayer or inter-layer or interlevel or inter-level) and ((slot or slit or via or opening or hole) near10 (dimension or width or length or longer or shorter or larger)) same (active or source or drain or source/drain)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:08
L38	<b>289</b>	((bit or bitline) same (slot or slit or via or opening or hole)) same (contact or contactless) same (insulating or dielectric or ild or interlayer or inter-layer or interlevel or inter-level) and ((slot or slit or via or opening or hole) near10 (dimension or width or length or longer or shorter or larger)) same (active or source or drain or source/drain) same gate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:08

		•	•	-		
L39	302	((bit or bitline) same (slot or slit or via or opening or hole)) same (contact or contactless) same (insulating or dielectric or ild or interlayer or inter-layer or interlevel or inter-level) and ((slot or slit or via or opening or hole) near10 (dimensional or dimension or width or length or longer or shorter or larger)) same (active or source or drain or source/drain) same gate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:09
L40	189	((bit or bitline) same (slot or slit or via or opening or hole)) same (contact or contactless) same (insulating or dielectric or ild or interlayer or inter-layer or interlevel or inter-level) and ((slot or slit or via or opening or hole) near10 (dimensional or dimension or width or length or longer or shorter or larger)) same (active or source or drain or source/drain) same gate and ((slot or slit or via or opening or hole) near10 (resist or photoresist or lithography or photolithography or image or imaging or imaged))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:10
L61	20311	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/E21.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/257.ccls. or 438/261. ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.33.ccls.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:16
L62	1037	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103.ccls. or 438/128.ccls. or 438/129.ccls. or 438/257.ccls. or 438/261.ccls. or 438/263.ccls. or 438/197.ccls. or 365/185.01.ccls. or 365/185.33.ccls.) and ((slot or slit or opening or hole or via) with (bit or bitline or bit-line) with (insulating or dielectric or ild or insulation or interlayer or inter-layer or inter-level))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:17

			1			T
L63	677	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/257.ccls. or 438/261. ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.01.ccls. or 365/185.01.ccls. or opening or hole or via) with (bit or bitline or bit-line) with (insulating or dielectric or ild or insulation or interlayer or inter-layer or inter-level or inter-level)) same (active or source or drain)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:17
L64	551	(257/314:ccls. or 257/315:ccls. or 257/316:ccls. or 257/317:ccls. or 257/390:ccls. or 257/391:ccls. or 257/E21.682:ccls. or 257/E27.103:ccls. or 438/128:ccls. or 438/129:ccls. or 438/257:ccls. or 438/261:ccls. or 438/263:ccls. or 438/261:ccls. or 365/185:01:ccls. or 365/185:01:ccls. or 365/185:01:ccls. or 365/185:01:ccls. or it or opening or hole or via) with (bit or bitline or bit-line) with (insulating or dielectric or ild or insulation or interlayer or inter-layer or inter-level)) with (active or source or drain)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:17
L65	107	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/257.ccls. or 438/261. ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.01.ccls. or 365/185.01.ccls. or 365/185.01.ccls. or intercellation or inter	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:18

		*				
L66	293	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/257.ccls. or 438/261. ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.01.ccls. or 365/185.03.ccls.) and ((slot or slit or opening or hole or via) same (bit or bitline or bit-line) same (insulating or dielectric or ild or insulation or interlayer or inter-layer or inter-level or inter-level)) same (active or source or drain) and ((dimension or dimensional or length or width) near10 (slit or slot or opening or hole or via))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:19
L67	159	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103.ccls. or 438/128.ccls. or 438/129.ccls. or 438/257.ccls. or 438/261.ccls. or 438/263.ccls. or 438/197.ccls. or 365/185.01.ccls. or 365/185.33.ccls.) and ((slot or slit or opening or hole or via) same (bit or bitline or bit-line) same (insulating or dielectric or ild or insulation or interlayer or inter-layer or inter-level) same (active or source or drain) and ((dimension or dimensional or length or width) near10 (slit or slot or opening or hole or via)) and ((slot or via or opening or slit or hole) near10 (image or imaging or imaged or resist or photoresist or lithography) or photolithography))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	O	2007/12/05 12:20

L68 1		(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/257.ccls. or 438/261. ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.01.ccls. or 365/185.33.ccls.) and ((slot or slit or opening or hole or via) same (bit or bitline or bit-line) same (insulating or dielectric or ild or insulation or interlayer or inter-layer or interlevel or inter-level)) same (active or source or drain) and ((dimension or dimensional or length or width) near10 (slit or slot or opening or hole or via)) and ((slot or via or opening or slit or hole) near10 (image or imaging or imaged or resist or photoresist or lithography or photolithography)) and ((slot or slit or via or opening or hole) near10 (contact or contactless))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:22
L69 1	07	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103.ccls. or 438/128.ccls. or 438/129.ccls. or 438/257.ccls. or 438/261.ccls. or 438/263.ccls. or 438/197.ccls. or 365/185.01.ccls. or 365/185.01.ccls. or 365/185.33.ccls.) and ((slot or slit or opening or hole or via) same (bit or bitline or bit-line) same (insulating or dielectric or ild or insulation or interlayer or inter-layer or interlevel or inter-level)) same (active or source or drain) and ((dimension or dimensional or length or width) near10 (slit or slot or opening or hole or via)) and ((slot or via or opening or slit or hole) near10 (image or imaging or imaged or resist or photoresist or lithography or photolithography)) and ((slot or slit or via or opening or hole) near10 (contact or contactless) near10 (bit or bitline or bit-line))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:25

	· · · · · · · · · · · · · · · · · · ·			,	
L70 76	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/257.ccls. or 438/261. ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.33.ccls.) and ((slot or slit or opening or hole or via) same (bit or bitline or bit-line) same (insulating or dielectric or ild or insulation or interlayer or inter-layer or interlevel or inter-level)) same (active or source or drain) and ((dimension or dimensional or length or width) near10 (slit or slot or opening or hole or via)) and ((slot or via or opening or slit or hole) near10 (image or imaging or imaged or resist or photoresist or lithography or photolithography)) and ((slot or slit or via or opening or hole) near10 (contact or contactless) near10 (bit or bitline or bit-line)) and ((slot or slit or opening or hole) near10 gate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:25

257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:26

. 72		(257/244 ) 257/245 )	LIC DODUC		011	2007/12/05 12 27
L72	45	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or	US-PGPUB; USPAT;	OR	ON	2007/12/05 12:27
		257/390.ccls. or 257/391.ccls. or	EPO; JPO;			
		257/E21.682.ccls. or 257/E27.103.	DERWENT;			
İ		ccls. or 438/128.ccls. or 438/129.	IBM TDB			
		ccls. or 438/257.ccls. or 438/261.	_			
		ccls. or 438/263.ccls. or 438/197.				
	•	ccls. or 365/185.01.ccls. or				
		365/185.33.ccls.) and ((slot or slit				
		or opening or hole or via) same				
		(bit or bitline or bit-line) same				
		(insulating or dielectric or ild or insulation or interlayer or				
		inter-layer or interlevel or				
		inter-level)) same (active or				
		source or drain) and ((dimension				
		or dimensional or length or width)				
		near10 (slit or slot or opening or				
		hole or via)) and ((slot or via or				
		opening or slit or hole) near10				
		(image or imaging or imaged or				
		resist or photoresist or lithography				
		or photolithography)) and ((slot or				
		slit or via or opening or hole) near10 (contact or contactless)				
		near10 (contact of contactiess)				
		and ((slot or slit or opening or	•			
		hole or via) near10 (expose or				
		exposing or exposed) near10				
		gate)				

· · · · · · · · · · · · · · · · · · ·				
L73 7 (257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/263.ccls. or 438/261. ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.33.ccls.) and ((slot or slit or opening or hole or via) same (bit or bitline or bit-line) same (insulating or dielectric or ild or insulation or interlayer or inter-layer or inter-level)) same (active or source or drain) and ((dimension or dimensional or length or width) near10 (slit or slot or opening or hole or via)) and ((slot or via or opening or slit or hole) near10 (image or imaging or imaged or resist or photoresist or lithography or photolithography)) and ((slot or slit or via or opening or hole) near10 (contact or contactless) near10 (bit or bitline or bit-line)) and ((slot or slit or opening or hole or via) near10 (expose or exposing or exposed) near10 gate) and ((slot or slit or hole or opening or via) near10 (dimension or dimensional))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:28

174		(257/214 cala au 257/215 cala au	HC DCDHD	OD	ON	2007/12/05 12:20
L74	1	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or	US-PGPUB; USPAT;	OR	ON	2007/12/05 12:29
		257/310.ccls. or 257/317.ccls. or 257/390.ccls. or	EPO; JPO;			
		257/390.ccis. of 257/391.ccis. of 257/E21.682.ccls. or 257/E27.103.	DERWENT;			
		ccls. or 438/128.ccls. or 438/129.	IBM_TDB			
		ccls. or 438/257.ccls. or 438/261.	1011_100			
		ccls. or 438/263.ccls. or 438/197.				
		ccls. or 365/185.01.ccls. or				
		365/185.33.ccls.) and ((slot or slit				
		or opening or hole or via) same				
		(bit or bitline or bit-line) same				
:		(insulating or dielectric or ild or				
		insulation or interlayer or				
		inter-layer or interlevel or				
		inter-level)) same (active or				
		source or drain) and ((dimension				
		or dimensional or length or width)				
		near10 (slit or slot or opening or				
		hole or via)) and ((slot or via or				
		opening or slit or hole) near10				
		(image or imaging or imaged or				
		resist or photoresist or lithography				
		or photolithography)) and ((slot or				
		slit or via or opening or hole)				
		near10 (contact or contactless)				
		near10 (bit or bitline or bit-line))				
		and ((slot or slit or opening or				
		hole or via) near10 (expose or				
		exposing or exposed) near10				
		gate) and ((slot or slit or hole or				
		opening or via) near10 (dimension		•		
		or dimensional)) and contactless				

L75	(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/257.ccls. or 438/261. ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.01.ccls. or 365/185.33.ccls.) and ((slot or slit or opening or hole or via) same (bit or bitline or bit-line) same (insulating or dielectric or ild or insulation or interlayer or inter-layer or inter-level)) same (active or source or drain) and ((dimension or dimensional or length or width) near10 (slit or slot or opening or hole or via)) and ((slot or via or opening or slit or hole) near10 (image or imaging or imaged or resist or photoresist or lithography or photolithography)) and ((slot or slit or via or opening or hole) near10 (contact or contactless) near10 (bit or bitline or bit-line)) and ((slot or slit or opening or hole or via) near10 (expose or exposing or exposed) near10 gate) and contactless	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:29

257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/221.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/257.ccls. or 438/261. ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.33.ccls.) and ((slot or slit or opening or hole or via) same (bit or bitline or bit-line) same (insulating or dielectric or ild or insulation or interlayer or inter-layer or inter-level)) same (active or source or drain) and ((dimension or dimensional or length or width) near10 (slit or slot or opening or hole or via)) and ((slot or via or opening or slit or hole) near10 (image or imaging or imaged or resist or photoresist or lithography				I*	T	T	1
slit or via or opening or hole) near10 (contact or contactless) near10 (bit or bitline or bit-line)) and ((slot or slit or opening or hole or via) near10 (expose or exposing or exposed) near10 gate) and (contactless or (contact near10 (without or simultaneous	L76	24	257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/257.ccls. or 438/261. ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.33.ccls.) and ((slot or slit or opening or hole or via) same (bit or bitline or bit-line) same (insulating or dielectric or ild or insulation or interlayer or inter-layer or inter-level or inter-level)) same (active or source or drain) and ((dimension or dimensional or length or width) near10 (slit or slot or opening or hole or via)) and ((slot or via or opening or slit or hole) near10 (image or imaging or imaged or resist or photoresist or lithography or photolithography)) and ((slot or slit or via or opening or hole) near10 (contact or contactless) near10 (bit or bitline or bit-line)) and ((slot or slit or opening or hole or via) near10 (expose or exposing or exposed) near10 gate) and (contactless or (contact	EPO; JPO; DERWENT;	OR	ON	2007/12/05 12:30

[.==	20	(257/244   257/245				2007/10/27 12 77
L77		(257/314.ccls. or 257/315.ccls. or 257/316.ccls. or 257/317.ccls. or 257/390.ccls. or 257/391.ccls. or 257/E21.682.ccls. or 257/E27.103. ccls. or 438/128.ccls. or 438/129. ccls. or 438/257.ccls. or 438/261. ccls. or 438/263.ccls. or 438/197. ccls. or 365/185.01.ccls. or 365/185.33.ccls.) and ((slot or slit or opening or hole or via) same (bit or bitline or bit-line) same (insulating or dielectric or ild or insulation or interlayer or inter-layer or inter-layer or inter-level or inter-level)) same (active or source or drain) and ((dimension or dimensional or length or width) near10 (slit or slot or opening or hole or via)) and ((slot or via or opening or slit or hole) near10 (image or imaging or imaged or resist or photoresist or lithography or photolithography)) and ((slot or slit or via or opening or hole) near10 (contact or contactless) near10 (bit or bitline or bit-line)) and ((slot or slit or opening or hole or via) near10 (expose or exposing or exposed) near10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/05 12:32
		gate) and (contactless or (contact near10 (without or simultaneous or time or simultaneously)))				

L78  34 (257/314.ccls. or 257/315.ccls. 257/316.ccls. or 257/317.ccls. 257/390.ccls. or 257/391.ccls. 257/890.ccls. or 257/E27.3 ccls. or 438/128.ccls. or 438/128.ccls. or 438/26 ccls. or 438/263.ccls. or 438/26 ccls. or 438/263.ccls. or 438/185.33.ccls.) and ((slot or or opening or hole or via) same (bit or bitline or bit-line) same (insulating or dielectric or ild or insulation or interlayer or inter-layer or inter-level)) same (active or source or drain) and ((dimensic or dimensional or length or wid near10 (slit or slot or opening or hole or via)) and ((slot or via o opening or slit or hole) near10 (image or imaging or imaged or resist or photoresist or lithogra or photolithography)) and ((slot slit or via or opening or hole) near10 (contact or contactless) near10 (bit or bitline or bit-line and ((slot or slit or opening or hole or via) near10 (expose or exposing or exposed) near10 gate) and ((self near (align or aligning or aligned or alignmen or contactless or (contact near1 (without or simultaneous or tim s	or USPAT; EPO; JPO; DERWENT; IBM_TDB  1. 7. Slit  or o